

## R\_74\_IPS2200\_10X36\_OD97\_ID66

Date: 20.10.2019

Project: R\_74\_V10\_IPS2200\_10X36\_OD97\_ID66.PrjPcb

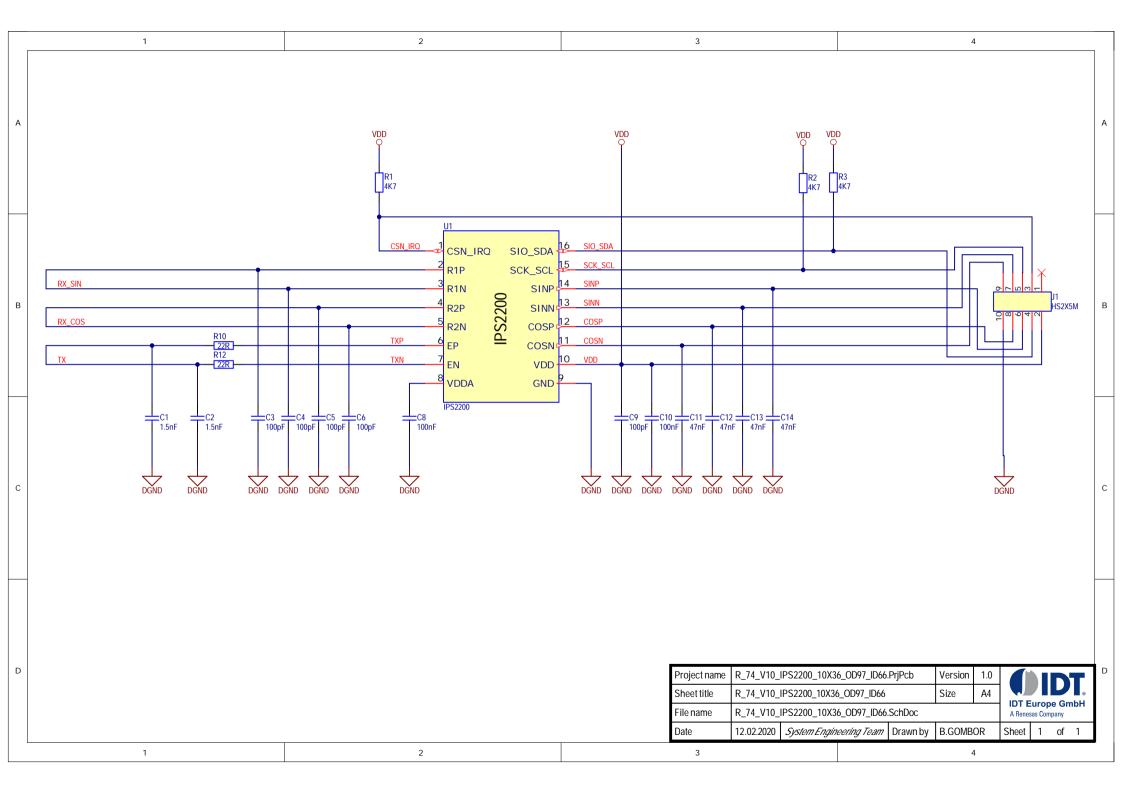
Version 1.0

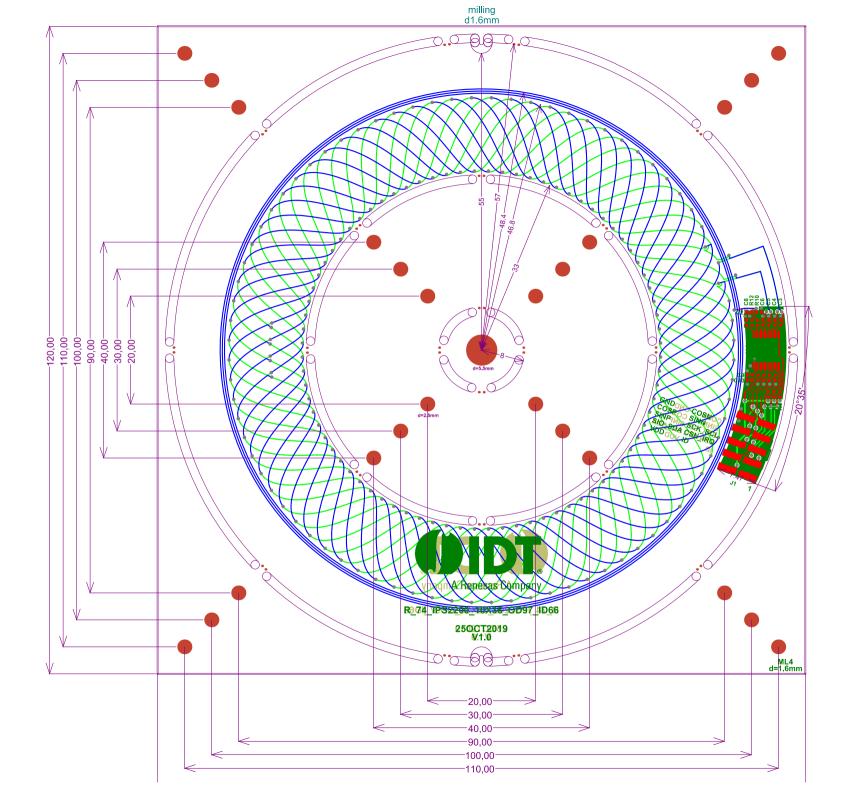
Content: Schematic

Coil PCB Layout
Coil PCB 3D Model
Bill of Materials

**PCB Manifacture Requirements** 

Coil Layer Stack
Target PCB Layout
Target PCB 3D Model





## **Board Stack Report**

| Stack Up |                          | Layer Stack           |               |           |          |  |
|----------|--------------------------|-----------------------|---------------|-----------|----------|--|
| Layer    | <b>Board Layer Stack</b> | Name                  | Material      | Thickness | Constant |  |
| 1        |                          | Top Paste             |               |           |          |  |
| 2        |                          | Top Overlay           |               |           |          |  |
| 3        |                          | Top Solder            | Solder Resist | 0,030mm   | 3,5      |  |
| 4        |                          | Top Layer             | Copper        | 0,035mm   |          |  |
| 5        |                          | Dielectric 1          | FR-4          | 0,110mm   | 4,29     |  |
| 6        |                          | Inner Layer 1         | Copper        | 0,035mm   |          |  |
| 7        |                          | Dielectric 3          | FR-4          | 1,180mm   | 3,96     |  |
| 8        |                          | InnerLayer 2          | Copper        | 0,035mm   |          |  |
| 9        |                          | Dielectric 2          | FR-4          | 0,110mm   | 4,29     |  |
| 10       |                          | Bottom Layer          | Copper        | 0,035mm   |          |  |
| 11       |                          | Bottom Solder         | Solder Resist | 0,030mm   | 3,5      |  |
| 12       |                          | <b>Bottom Overlay</b> |               |           |          |  |
| 13       |                          | <b>Bottom Paste</b>   |               |           |          |  |
|          | Height : 1,600mm         |                       |               |           |          |  |

| Designator         | Value   | Quantity | Footprint           |
|--------------------|---------|----------|---------------------|
| C1, C2             | 1.5nF   | 2        | C0402 3D            |
| R1, R2, R3         | 4K7     | 3        | R0402 3D            |
| R10, R12           | 22R     | 2        | R0402 3D            |
| C11, C12, C13, C14 | 47nF    | 4        | C0402 3D            |
| C8, C10            | 100nF   | 2        | C0402 3D            |
| C3, C4, C5, C6, C9 | 100pF   | 5        | C0402 3D            |
| J1                 | HS2X5M  | 1        | T821M110A1S100CEU-B |
| U1                 | IPS2200 | 1        | TSSOP16_NVT02006    |

## Manufacturing requirements

Name R\_74\_V10\_IPS2200\_10X36\_OD97\_ID66

Number of layers 4

Base material FR-4

Thickness 1.6 mm +/- 10%

Thickness of copper coating 35 µm
Final cover ENIG
Minimal copper width 0.2 mm
Minimal copper to copper distance 0.15 mm
Via hole/pad diameter 0.3/0.6 mm

Slotted holes d1.6mm milling path

Panel dimensions 120 x 120 mm

Silk screen color white on BOTH sides

Solder mask color green

